



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D * : Required Field

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2019-02-14
Company Unique ID	NL 008751171801		
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact Phone *	Refer to Supplier Comment section	Contact Email *	Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement		
Supplier Acceptance *	true	Legal Declaration *
		Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
SCTH35N65G2V-7AG	T28P*SQF9AYE	A	SH1A	2019-02-14
	Amount	UoM	Unit type	ST ECOPACK Grade
	1450	mg	Each	ECOPACK® 1
Comment	ECOPACK® or ECOPACK® 1 is STMicroelectronics trade name for ROHS compliant devices			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	245	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DIP	10.2 - 9.15 - 4.5	7	Through-hole	
Comment	H2PAK-7			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 26th October 2018			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	1.24	Die - Leadframe	852
Lead	5.03	Soft solder	3469
Antimony trioxide	9.73	Mold compound	6710

QueryList : REACH-15th January 2019				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	5.03	Soft solder	3469
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	5.03	Soft solder	955003

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	T28P*5QF9AYE					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	8.808	mg	supplier	die	Silicium carbide	409-21-2		8.585	mg	974682	5921
				supplier	metallization	Aluminium (Al)	7429-90-5		0.111	mg	12602	77
				supplier	Passivation	Silicon Oxide	7631-86-9		0.039	mg	4428	27
				supplier	back side metallization	Titanium (Ti)	7440-32-6		0.003	mg	341	2
				supplier	back side metallization	Gold (Au)	7440-57-5		0.008	mg	908	6
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.038	mg	4314	26
Leadframe	M-004 Copper and its alloys	621.324	mg	supplier	polymer die coating	PIX1 Polyimide	108-65-6		0.024	mg	2725	17
				supplier	alloy	Copper (Cu)	7440-50-8		619.314	mg	996765	427113
				supplier	alloy	Iron (Fe)	7439-89-6		0.285	mg	459	197
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.521	mg	838	358
				supplier	metallization	Nickel (Ni)	7440-02-0		1.197	mg	1927	826
				supplier	metallization	Phosphorus (P)	7723-14-0		0.007	mg	11	5
Soft solder	Solder	5.267	mg	SVHC	solder	Lead (Pb)	7439-92-1	7a-Lead in high met	5.030	mg	955003	3469
				supplier	solder	Silver (Ag)	7440-22-4		0.132	mg	25062	91
				supplier	solder	Tin (Sn)	7440-31-5		0.105	mg	19935	72
Bonding wires	M-011 Other inorganic materials	1.079	mg	supplier	wire	Aluminium (Al)	7429-90-5		1.077	mg	998146	743
				supplier	wire	Magnesium (Mg)	7439-95-4		0.002	mg	1854	1
Encapsulation	M-011 Other inorganic materials	811.084	mg	supplier	mold compound	Silica, vitreous	60676-86-0		667.522	mg	823000	460360
				supplier	mold compound	Epoxy Cresol Novolak	29690-82-2		56.776	mg	70000	39156
				supplier	mold compound	Phenol resin	9003-35-4		32.443	mg	40000	22374
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		24.333	mg	30001	16781
				supplier	mold compound	Antimony Trioxide	1309-64-4		9.733	mg	12000	6712
				supplier	mold compound	Brominated Epoxy Resin	40039-93-8		16.222	mg	20000	11188
				supplier	mold compound	Carbon black	1333-86-4		4.055	mg	4999	2797
Connections coating	Solder	2.438	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.438	mg	1000000	1681